

# **TCR-1003**

## Thermal Conductive Dual-Curable Epoxy Adhesive

#### PRODUCT DESCRIPTION:

- Base chemistry: epoxy only, cationic polymerization
- One component Boron Nitride filled non-electrically conductive adhesive ready for use, solvent-free, UV and heat curing, thixotropic
- Average particle size 2 μm and max size 10 μm

#### **PRODUCT USE:**

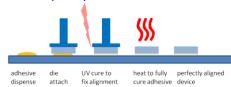
- Bonding integrated circuits and components in semiconductor packaging.
- Heat transfer and heat dissipate
- Bonding of opaque substrates

### **FEATURES:**

 Thermal conductive and electrical insulating, epoxy only, high adhesion, high Tg, long shelf and working life, low outgas, excellent reliability performances, robust for solder reflow process

## **INSTRUCTIONS FOR USE:**

- Clean the substrates to remove contamination, dust, moisture, salt and/or oil
- 2) Dispense adhesive on substrates
- 3) Bond substrates (with active alignment optional)
- 4) UV cure to fix alignment
- 5) Thermal cure: heat is mandatory for completely cured adhesive



## **GENERAL USAGE INFORMATION:**

**Shipment**: no restriction on shipment and no cold shipment is needed

**Storage:** After the adhesive is received in black syringes or amber HDPE bottles, room temperature storage (15-30°C) in the original container is required.

## SAFETY AND HANDLING

The uncured adhesive can be cleaned from apparatus with isopropyl alcohol (IPA), methyl ethyl ketone (MEK), or commercial alcohol based cleaning solution. Avoid direct skin and eye contact. Use only in well ventilated areas. Use protective clothing, gloves and safety goggles. Read Material Safety Data Sheet before handling.

## CURING CONDITIONS: 2 curing ways: UV + heat or heat

 UV + Heat curing: fix aligned parts with UV, then use heat to completely cure adhesive including adhesive in shaded areas.

## First step: UV cure

\*Metal halide/Mercury UV: UV-A (320-400 nm),intensity: 100-1,000 mW/cm<sup>2</sup> \*LED-365 nm, UV light intensity: 100 to 1,000 mW/ cm<sup>2</sup>

	LED-365 nm  UV intensity(mW/cm²) x time (sec)		Metal Halide/Mercury(UV-A: 320-400 nm)  UV intensity(mW/cm²) x time (sec)	
	100	100 sec or more	100	50 sec or more
	or 200	50 sec or more	or 200	25 sec or more
	or 300	35 sec or more	or 300	17 sec or more
	or 400	25 sec or more	or 400	13 sec or more
	or 500	20 sec or more	or 500	10 sec or more
	or 1.000	10 sec or more	or 1.000	5 sec or more

<u>Second step: heat cure</u>: the adhesive is exposed to UV light first, then heat cure at  $150\,^{\circ}\text{C}$  for 120 to 180 minutes

- 2) **Heat curing**: the adhesive will cure by only heat 150°C for 2-4 hrs or 180°C for 30 to 60 minutes
- The actual heat cure time is dependent on the heating time of the bonded components. The heat time of the components must be added to the total cure time of the adhesive for the process
- The effect of humidity is greater for very thin film, if the adhesive layer is <25  $\mu$ m, then longer cure time might be needed
- To ensure good curing speed, the humidity should be <60% RH</li>
- Epoxy adhesives have post cure properties. Adhesion strength testing should be conducted at least 24 hrs after part assembly.

## **TYPICAL PROPERTIES**

## Uncured resin

Viscosity at 25 °C, mPa.s or cps (shear rate: 10/s)	70,000 to 85,000			
Thixotropic index (shear rate: 1/s over 10/s)	4			
Appearance of uncured adhesive	white paste			
Shelf life (20 – 25 °C)	6 months			
Work life (Pot life) (20 – 25 °C)	3 months			
Density (g/mL)	1.3			
<u>Cured film</u>				
Shrinkage (linear, %)	< 0.3			
Hardness – Shore D	85			
Outgas, weight % (per MIL-STD 883/5011)	0.08			
Outgas, weight % (per Telcordia GR-1221)	0.06			
Glass transition temperature (DMA, °C)	166			
Volume Resistivity, ohm-cm	>10 <sup>13</sup>			
<u>Thermal Properties</u>				
Thermal Conductivity:	2.6 W/m °K (75 μm film)			
	1.25 W/m°K (500 μm film)			
Coefficient of thermal expansion (DMA)				
below Tg (x10 <sup>-6</sup> ), °C <sup>-1</sup>	20			
above Tg (x10 <sup>-6</sup> ), °C <sup>-1</sup>	59			
Physical properties tested at 25°C, 50% RH (ASTM D638)				
Tensile strength, MPa	150			
Elongation (%)	3			
Young's Modulus, MPa	15,900			
Operating temperature, °C	-60 to 200			

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